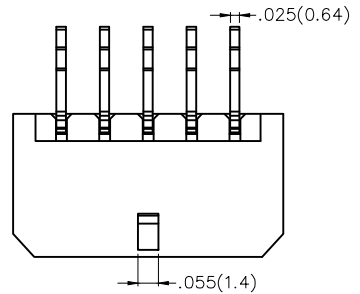


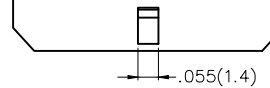
1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Size change	22/JUL/19	KATE	CHERRY
2		Structure and Size change	12/JUL/22	MATT	CHERRY
3		Structure and Size change	07/DEC/23	MATT	LEO

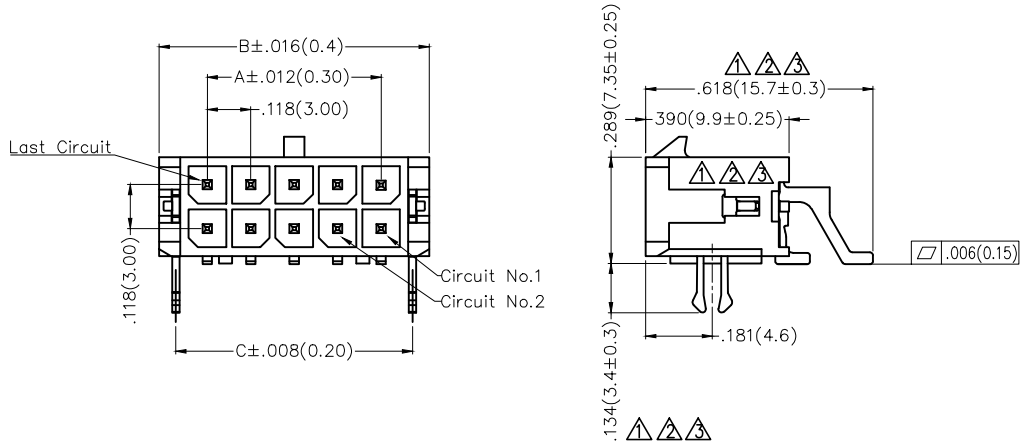
A



B



C



D

Electrical

Current Rating: 5.0A AC(rms)/DC  
 Voltage Rating: 250V AC(rms)/DC  
 Contact Resistance: 10 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 1500V AC r.m.s  
 Temperature Range—Operating: -25°C~+85°C

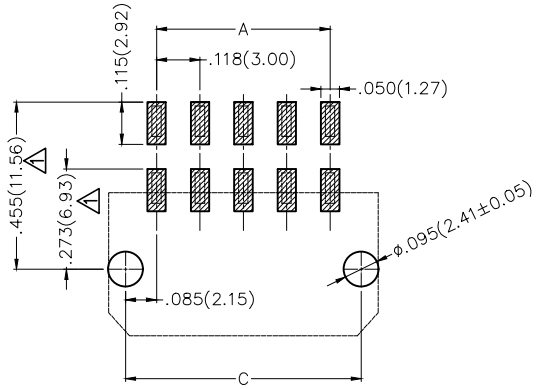
Material and Plating

Housing: LCP( UL 94V-0)  
 Contact Pin: Brass/ Tin Plated  
 Solder: Brass/ Tin Plated

Mates With (Housing): FHG30001 Series

Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
2	FWF30019-D02B23K6M	-	.262(6.65)	.167(4.30)
4	FWF30019-D04B23K6M	.118(3.00)	.380(9.65)	.287(7.30)
6	FWF30019-D06B23K6M	.236(6.00)	.498(12.65)	.406(10.30)
8	FWF30019-D08B23K6M	.354(9.00)	.616(15.65)	.524(13.30)
10	FWF30019-D10B23K6M	.472(12.00)	.734(18.65)	.642(16.30)
12	FWF30019-D12B23K6M	.591(15.00)	.852(21.65)	.760(19.30)
14	FWF30019-D14B23K6M	.709(18.00)	.970(24.65)	.878(22.30)
16	FWF30019-D16B23K6M	.827(21.00)	1.089(27.65)	.996(25.30)
18	FWF30019-D18B23K6M	.945(24.00)	1.207(30.65)	1.114(28.30)
20	FWF30019-D20B23K6M	1.063(27.00)	1.325(33.65)	1.232(31.30)
22	FWF30019-D22B23K6M	1.181(30.00)	1.443(36.65)	1.350(34.30)
24	FWF30019-D24B23K6M	1.299(33.00)	1.561(39.65)	1.469(37.30)

E



Recommended P.C.Board Layout

F

Ordering Information

FWF 300 19 — D XX B 2 3 K6 M  
 1 2 3 4 5 6 7 8 9 10

1   Category FWF—Wafer	2   Series Number 300—Pitch3.0mm	3   Distinction No. 19	4   Row Option D—Double Row	5   Circuits XX
6   Entry Angle B—90° Angle	7   Plating 2—Tin Plated	8   Material—Resin 3—LCP	9   Color—Resin K6—Black	10   Packaging M—Reel

THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone
DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.±5°		LEO	18/JUN/13	FWF30019-DXXB23K6M	FWF30019	
	X.X±.008(0.20)	.X'±2°		GISELLE	18/JUN/13	TITLE Wire to Board (Wafer) Pitch 3.0mm 90° Angled (SMT)		SHEET NO. 1/1
	X.XX±.006(0.15)	.XX'±1°				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5°	DRAWN BY KATE	DATE 18/JUN/13			

1 2 3 4 5 6 7 8